PCN Number: 2	0191103003		PCN Date:	Nov.	6, 201	L9	
Title: Datasheet for H	DC2010						
Customer Contact: PCN Manager				Dept:		Quality Services	
Change Type:							
Assembly Site		Design			Wafer	Bump Site	
Assembly Process		Data Sheet				Bump Material	
Assembly Materials		Part numbe				Bump Process	
Mechanical Specificat		est Site				Fab Site	
Packing/Shipping/Lab		est Proces	SS			Fab Materials	
					Wafer	Fab Process	
Notification Details							
Description of Change:							
Texas Instruments Incorp	orated is anno	uncing an	information on	lv not	ificatio	n.	
The product datasheet(s)							
The following change histo							
_	, ,						
TEXAS						UB 00040	
INSTRUMENTS				ON	HDC2010		
				SN	AS693C - c	JULY 2017-REVISED MAY 2019	
Changes from Revision B (August 2018) to Revision C						Page	
Added pin type description for DRDY/INT pin						3	
Changed description of behavior of TH_STATUS bit when INT_MODE is set to 1						11	
Changed description of behavior of TH_STATUS bit when INT_MODE is set to 0							
Changed description of behavior of TL_STATUS bit when INT_MODE is set to 1							
Changed description of behavior of TL_STATUS bit when INT_MODE is set to 0							
Changed description of behavior of HH_STATUS bit when INT_MODE is set to 1							
Changed description of behavior of HH_STATUS bit when INT_MODE is set to 0							
Changed description of behavior of HL_STATUS bit when INT_MODE is set to 1							
Changed description of behavior of HL_STATUS bit when INT_MODE is set to 0							
Changed the temperature resolution decoding from: 8 bit to: 9 bit							
	 Changed the humidity resolution decoding from: 8 bit to: 9 bit Changed the measurement configuration "10" bit encoding from: Humidity Only to: NA for field MEAS_CONFIG[1:0] 26 						
• Changed the measurement	configuration to bi	t encoding iro	om. Humidity Only to	5. NA 10	r neid ivi	EAS_CONFIG[1.0] 20	
The datasheet number will be changing.		Change From:		Τ,	^hong.	. To:	
Device Family		Change r	-rom:		Change	e 10:	
HDC2010		SNAS693	3B	5	SNAS6	93C	
These changes may be re	viewed at the o	datasheet l	links provided.				
			•				
http://www.ti.com/produc	CT/HDC2010						
Reason for Change:							
To accurately reflect device	ce characteristi	cs.					
Anticipated impact on I							
No anticipated impact. Th	is is a specifica	tion chang	ge announceme	ent on	ly. The	ere are no changes	
to the actual device. Changes to product ide	ntification ro	culting fr	om this DCN:				
-	nuncation re	suiting if	om uns PCN:				
None.							
Product Affected:	1		T				
HDC2010YPAR	HDC2010YPAT						

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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